

.025 SQ SOCKET HLE SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material: Black Liquid C US Black Liquid Crystal Polymer Contact Material: BeCu Plating:

Au over 50μ' (1,27μm) Ni Current Rating:

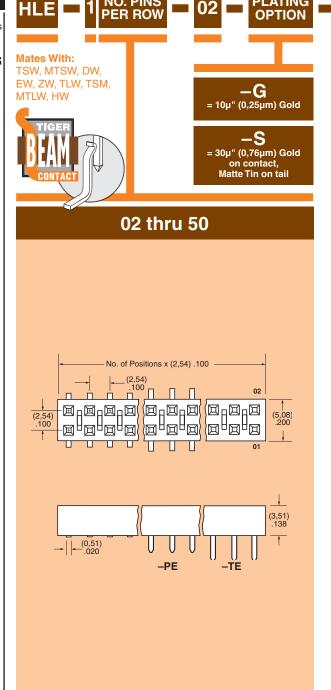
Current Hating: 2.5A @ 80°C ambient Operating Temp Range: -55°C to +125°C Insertion Depth: (1,78mm) .070" to (3,43mm) .135", pass-through, or (2,59mm) .102" min for bottom entry bottom entry

Insertion Force: (Single contact only) 2oz (0,56N) avg. Withdrawal Force: (Single contact only) 1.6oz (0,44N) avg. **RoHS Compliant:**

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max (02-20) (0,15mm) .006" max (21-50)



Leave blank for **Surface Mount** (3,66)

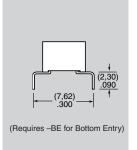
OPTION

(Requires -BE for Bottom Entry)

= Through-Hole Top Entry

(3,05)

= Through-hole Pass Through Entry



-BE = Bottom Entry (Requires Surface Mount or -PE)

OTHER

OPTION

= Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion



–LC = Locking Clip (2 positions min.)



= (6,50mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option

= Metal Pick & Place Pad (3 positions min.) (7,11) .280 (5,71) .225 (3,86) (152

= Tape & Reel Packaging (29 positions max.)

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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